Issue Date: 09-Aug-2014
Effective Date: 21-Nov-2014

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

Management Summary
NXP has changed the bonding wire diameter for all MFRC520, MFRC522, MFRC523 types to 18 µm.

Change Category

[ ] Wafer Fab process	[X] Assembly Process	[ ] Product Marking	[ ] Design
[ ] Wafer Fab materials	[ ] Assembly Materials	[ ] Electrical spec./Test coverage	[ ] Mechanical Specification
[ ] Wafer Fab location	[ ] Assembly Location	[ ] Test Location	[ ] Packing/Shipping/Labeling

Wire Diameter change for MFRC520, MFRC522, MFRC523

Details of this Change
NXP has changed the bonding wire diameter for all MFRC520, MFRC522, MFRC523 types from currently 25 µm to 18 µm. The change has been internally verified not to affect product functionality or reliability.

Why do we Implement this Change
Following our material policy to improve quality and to standardize materials where possible in line with materials used in that location.

Identification of Affected Products
Product identification does not change
Top side marking with production week.
The marking of the production date is setup in the third row: TnGYYCWx from 2014 (YY:14) in calendar week (CW: 46)

Product Availability
Sample Information
Samples are available from 31-Jul-2014
Production
Planned first shipment 14-Nov-2014

Impact
no impact to the product's functionality anticipated.

Data Sheet Revision
No impact to existing datasheet
Disposition of Old Products
Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 08-Sep-2014.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:
Name   Jean-François Tant
Position   Customer Quality Manager
e-mail address jean-francois.tant@nxp.com
At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

A global semiconductor company with operations in more than 25 countries, NXP posted unaudited revenue of $4.36 billion in 2012.

You have received this email because you are a designated contact or subscribed to NXP's Quallity Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

View Notification	Subscription	Support